

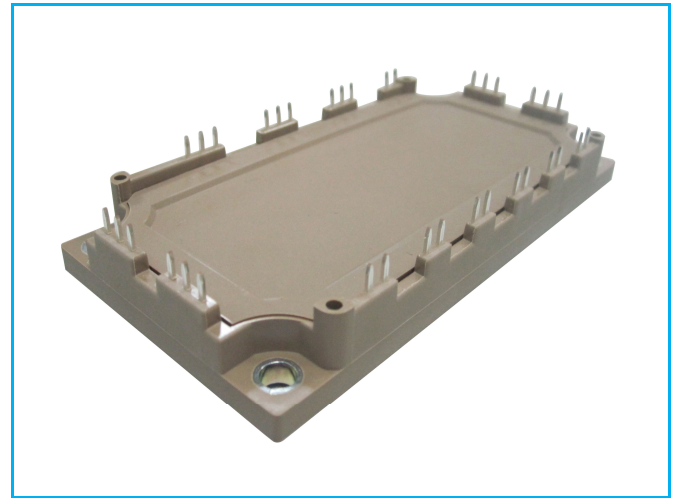
## PRODUCT FEATURES

- High level of integration
- IGBT CHIP(Trench+Field Stop technology)
- Low saturation voltage and positive temperature coefficient
- Fast switching and short tail current
- Free wheeling diodes with fast and soft reverse recovery
- Industry standard package with insulated copper base plate and soldering pins for PCB mounting

- Temperature sense included

## APPLICATIONS

- AC motor control
- Motion/servo control
- Inverter and power supplies



### IGBT-inverter

ABSOLUTE MAXIMUM RATINGS( $T_C=25^{\circ}\text{C}$  unless otherwise specified)

Symbol	Parameter/Test Conditions		Values	Unit
$V_{CES}$	Collector Emitter Voltage	$T_J=25^{\circ}\text{C}$	1200	V
$V_{GES}$	Gate Emitter Voltage		$\pm 20$	
$I_C$	DC Collector Current	$T_C=25^{\circ}\text{C}, T_{Jmax}=175^{\circ}\text{C}$	110	A
		$T_C=95^{\circ}\text{C}, T_{Jmax}=175^{\circ}\text{C}$	75	
$I_{CM}$	Repetitive Peak Collector Current	$t_p=1\text{ms}$	150	
$P_{tot}$	Power Dissipation Per IGBT	$T_C=25^{\circ}\text{C}, T_{Jmax}=175^{\circ}\text{C}$	385	W

### Diode-inverter

ABSOLUTE MAXIMUM RATINGS ( $T_C=25^{\circ}\text{C}$  unless otherwise specified)

Symbol	Parameter/Test Conditions		Values	Unit
$V_{RRM}$	Repetitive Reverse Voltage	$T_J=25^{\circ}\text{C}$	1200	V
$I_{F(AV)}$	Average Forward Current		75	A
$I_{FRM}$	Repetitive Peak Forward Current	$t_p=1\text{ms}$	150	
$I^2t$		$T_J=125^{\circ}\text{C}, t=10\text{ms}, V_R=0\text{V}$	1250	$\text{A}^2\text{S}$

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# MMG75W120X6TC

## IGBT-inverter

### ELECTRICAL CHARACTERISTICS ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/Test Conditions		Min.	Typ.	Max.	Unit
$V_{GE(th)}$	Gate Emitter Threshold Voltage	$V_{CE}=V_{GE}, I_C=3\text{mA}$	5.0	6.0	6.5	V
$V_{CE(sat)}$	Collector - Emitter Saturation Voltage	$I_C=75\text{A}, V_{GE}=15\text{V}, T_J=25^\circ\text{C}$		1.75	2.15	
		$I_C=75\text{A}, V_{GE}=15\text{V}, T_J=125^\circ\text{C}$		2.05		
		$I_C=75\text{A}, V_{GE}=15\text{V}, T_J=150^\circ\text{C}$		2.10		
$I_{CES}$	Collector Leakage Current	$V_{CE}=1200\text{V}, V_{GE}=0\text{V}, T_J=25^\circ\text{C}$			1	mA
		$V_{CE}=1200\text{V}, V_{GE}=0\text{V}, T_J=150^\circ\text{C}$			10	
$I_{GES}$	Gate Leakage Current	$V_{CE}=0\text{V}, V_{GE}=\pm 20\text{V}, T_J=25^\circ\text{C}$	-400		400	nA
$R_{gint}$	Integrated Gate Resistor			7.5		$\Omega$
$Q_g$	Gate Charge	$V_{CE}=600\text{V}, I_C=75\text{A}, V_{GE}=15\text{V}$		0.4		$\mu\text{C}$
$C_{ies}$	Input Capacitance	$V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=1\text{MHz}$		5		nF
$C_{res}$	Reverse Transfer Capacitance				220	
$t_{d(on)}$	Turn on Delay Time	$V_{CC}=600\text{V}, I_C=75\text{A}$ $R_G=3.6\Omega,$ $V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$		100	ns
			$T_J=125^\circ\text{C}$		120	ns
			$T_J=150^\circ\text{C}$		130	ns
$t_r$	Rise Time		$T_J=25^\circ\text{C}$		34	ns
			$T_J=125^\circ\text{C}$		36	ns
			$T_J=150^\circ\text{C}$		36	ns
$t_{d(off)}$	Turn off Delay Time	$T_J=25^\circ\text{C}$		290	ns	
		$T_J=125^\circ\text{C}$		350	ns	
		$T_J=150^\circ\text{C}$		370	ns	
$t_f$	Fall Time	$T_J=25^\circ\text{C}$		80	ns	
		$T_J=125^\circ\text{C}$		160	ns	
		$T_J=150^\circ\text{C}$		180	ns	
$E_{on}$	Turn on Energy	$T_J=125^\circ\text{C}$		9.7	mJ	
		$T_J=150^\circ\text{C}$		10.2	mJ	
$E_{off}$	Turn off Energy	$T_J=125^\circ\text{C}$		5.7	mJ	
		$T_J=150^\circ\text{C}$		6.1	mJ	
$I_{SC}$	Short Circuit Current	$t_{psc} \leq 10\mu\text{s}, V_{GE}=15\text{V}$ $T_J=150^\circ\text{C}, V_{CC}=800\text{V}$		280		A
$R_{thJC}$	Junction to Case Thermal Resistance (Per IGBT)				0.39	K/W

## Diode-inverter

### ELECTRICAL CHARACTERISTICS ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/Test Conditions		Min.	Typ.	Max.	Unit
$V_F$	Forward Voltage	$I_F=75\text{A}, V_{GE}=0\text{V}, T_J=25^\circ\text{C}$		1.75	2.15	V
		$I_F=75\text{A}, V_{GE}=0\text{V}, T_J=125^\circ\text{C}$		1.55		
		$I_F=75\text{A}, V_{GE}=0\text{V}, T_J=150^\circ\text{C}$		1.50		
$t_{rr}$	Reverse Recovery Time	$I_F=75\text{A}, V_R=600\text{V}$ $dI_F/dt=-2500\text{A}/\mu\text{s}$ $T_J=150^\circ\text{C}$		160		ns
$I_{RRM}$	Max. Reverse Recovery Current			128		A
$Q_{RR}$	Reverse Recovery Charge			14.7		$\mu\text{C}$
$E_{rec}$	Reverse Recovery Energy			5.8		mJ
$R_{thJCD}$	Junction to Case Thermal Resistance (Per Diode)				0.6	K/W

# MMG75W120X6TC

## NTC CHARACTERISTICS ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/Test Conditions	Min.	Typ.	Max.	Unit
$R_{25}$	Resistance $T_C=25^\circ\text{C}$		5		K $\Omega$
$B_{25/50}$	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298.15 \text{ K}))]$		3375		K

## MODULE CHARACTERISTICS ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/Test Conditions	Values	Unit	
$T_{Jmax}$	Max. Junction Temperature	175	°C	
$T_{Jop}$	Operating Temperature	-40~150		
$T_{stg}$	Storage Temperature	-40~125		
$V_{isol}$	Isolation Breakdown Voltage	AC, 50Hz(R.M.S), t=1minute	3000	V
CTI	Comparative Tracking Index		> 200	
Md	Mounting Torque	Recommended (M5)	2.5~5	Nm
Weight			300	g

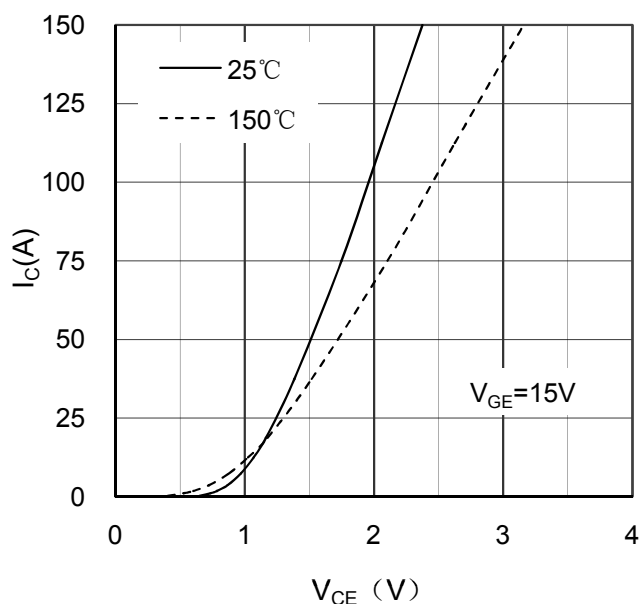


Figure 1. Typical Output Characteristics IGBT-inverter

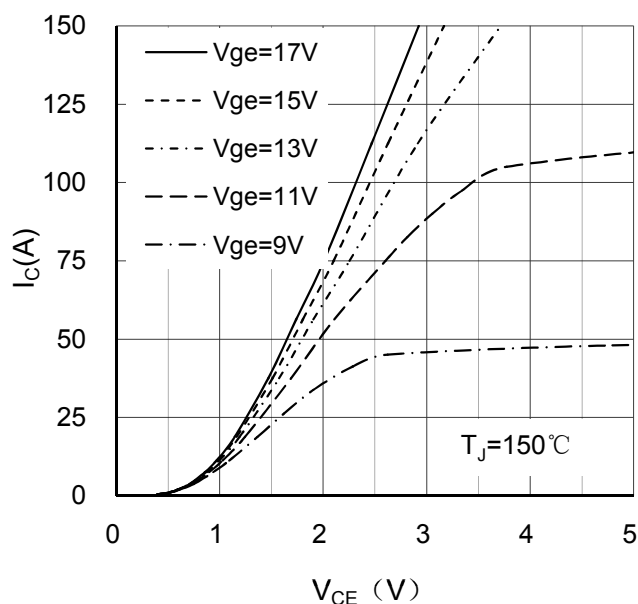


Figure 2. Typical Output Characteristics IGBT-inverter

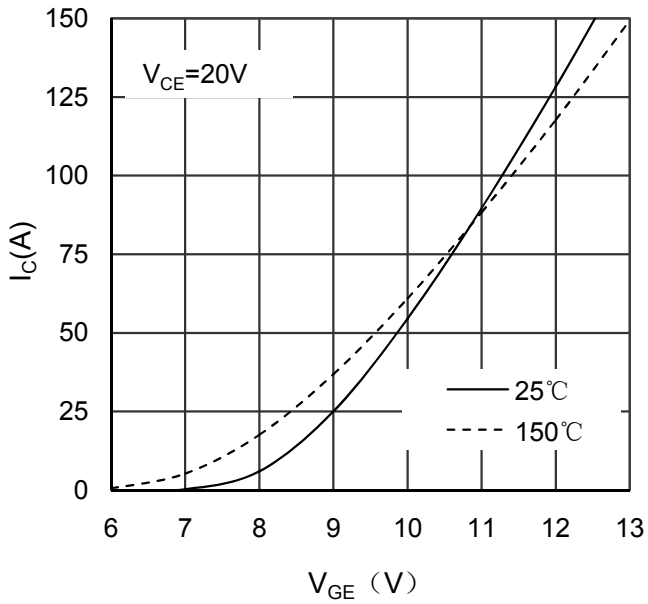


Figure 3. Typical Transfer characteristics IGBT-inverter

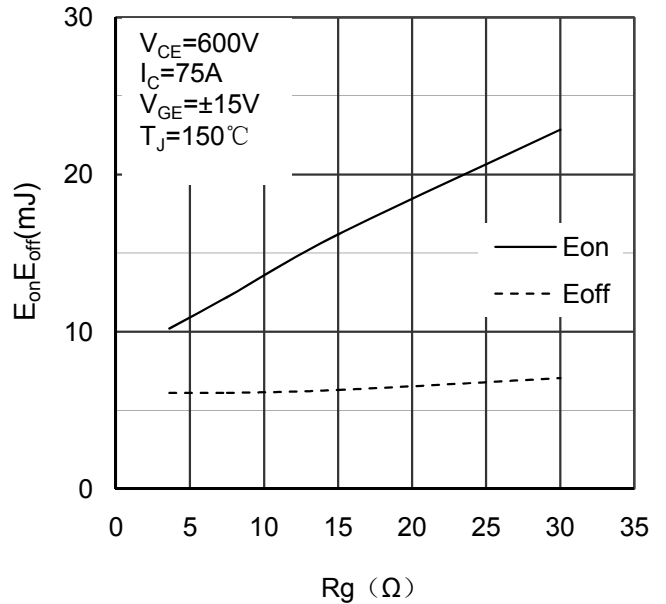


Figure 4. Switching Energy vs Gate Resistor IGBT-inverter

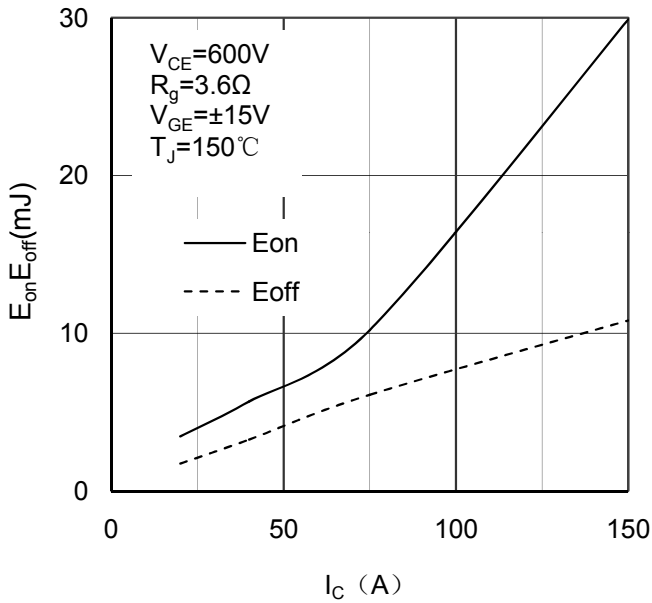


Figure 5. Switching Energy vs Collector Current IGBT-inverter

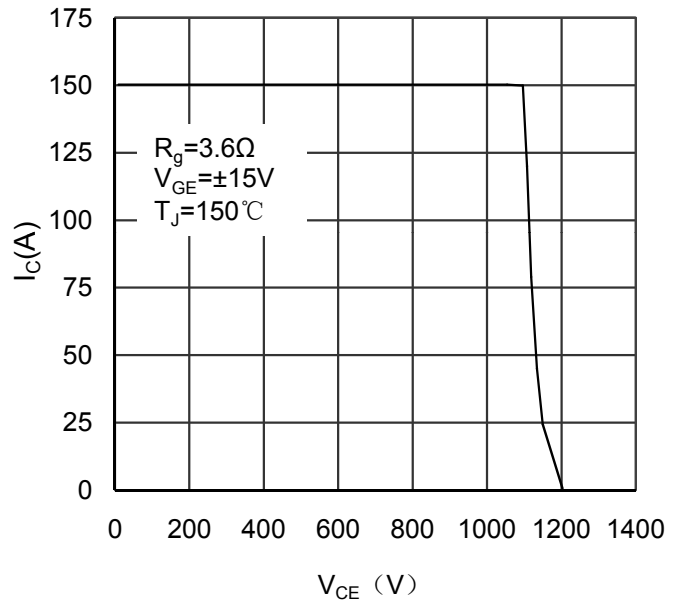


Figure 6. Reverse Biased Safe Operating Area IGBT-inverter

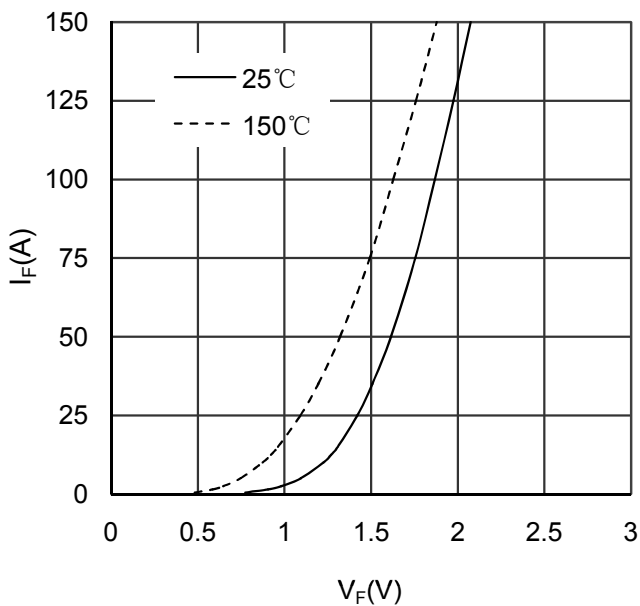


Figure 7. Diode Forward Characteristics Diode -inverter

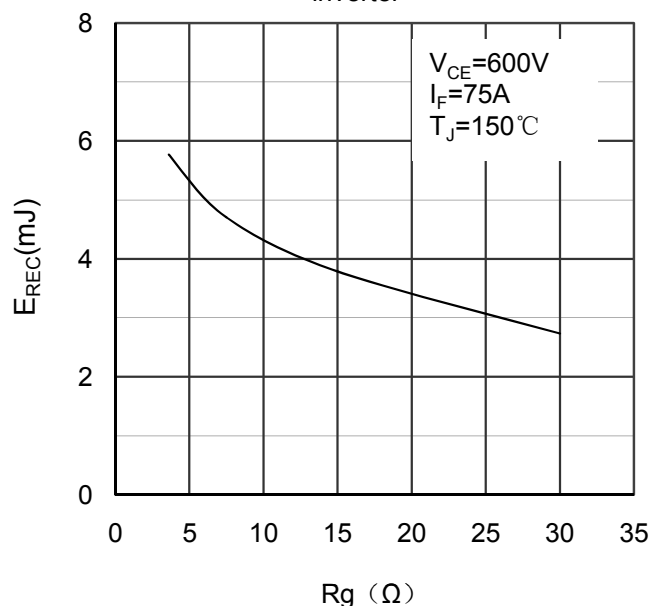


Figure 8. Switching Energy vs Gate Resistor Diode -inverter

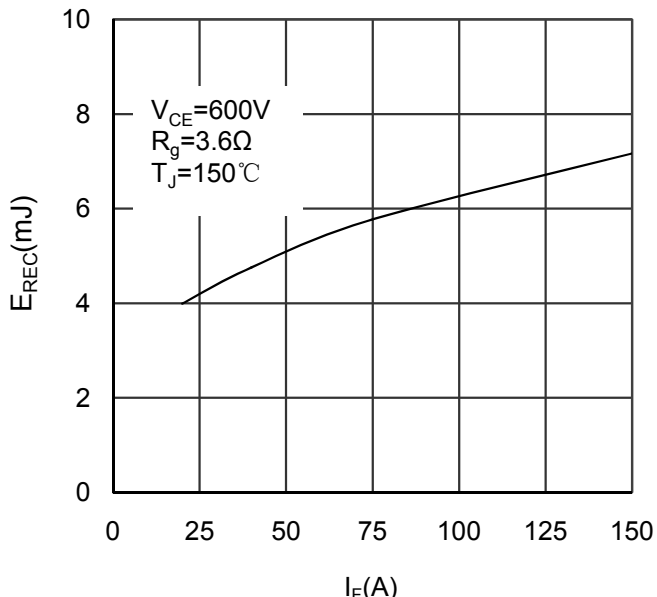


Figure 9. Switching Energy vs Forward Current Diode-inverter

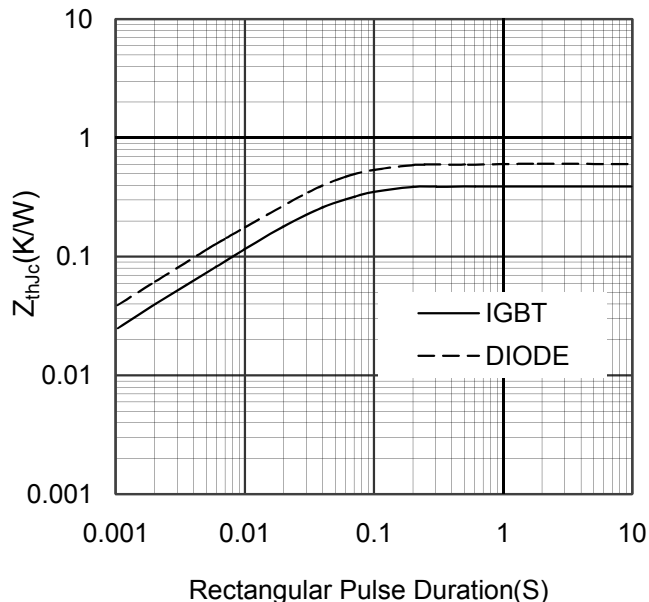


Figure 10. Transient Thermal Impedance of Diode and IGBT-inverter

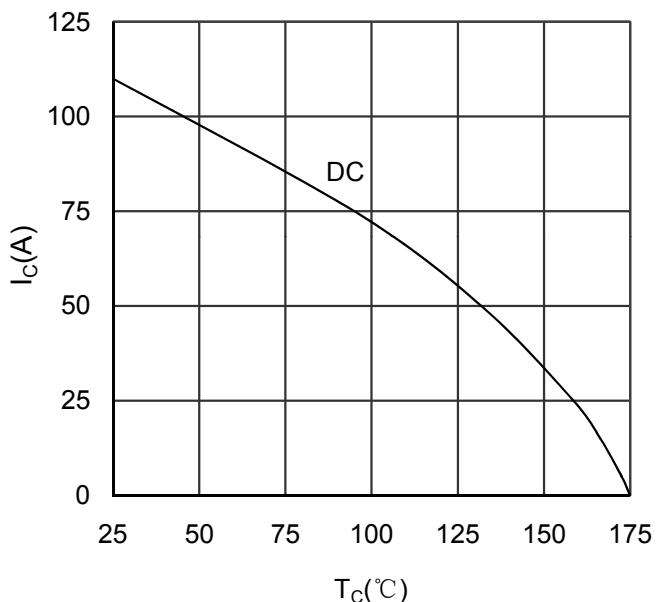


Figure 11. Collector Current vs Case temperature IGBT -inverter

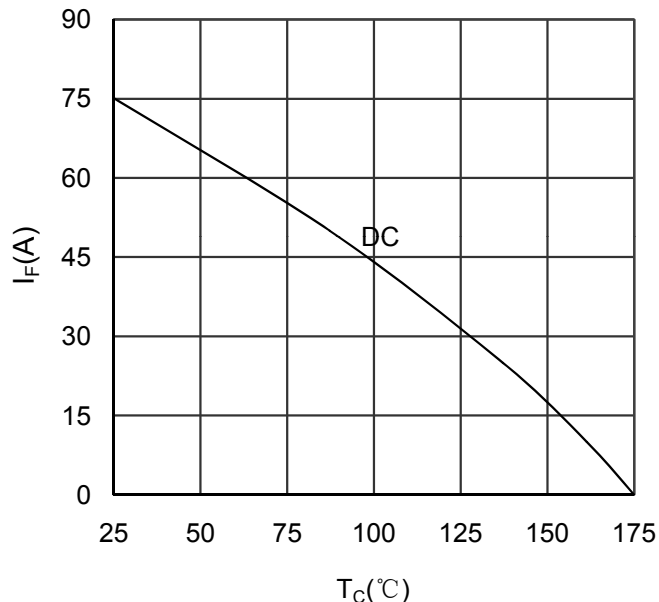


Figure 12. Forward current vs Case temperature Diode -inverter

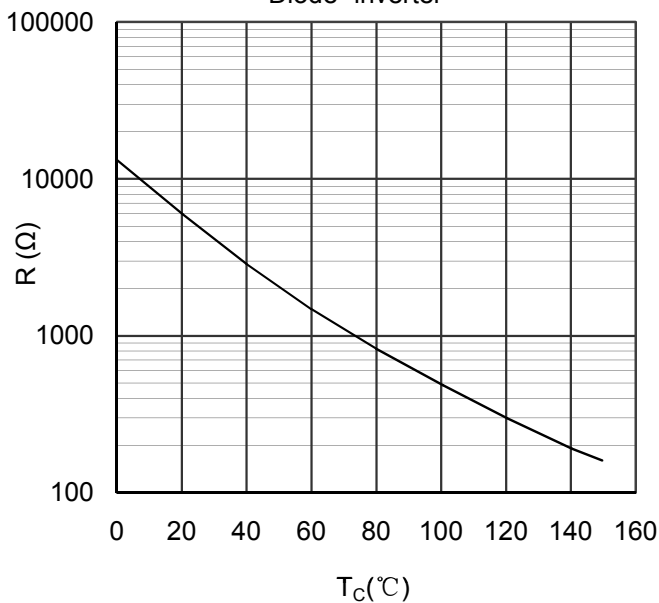


Figure 13. NTC Characteristics

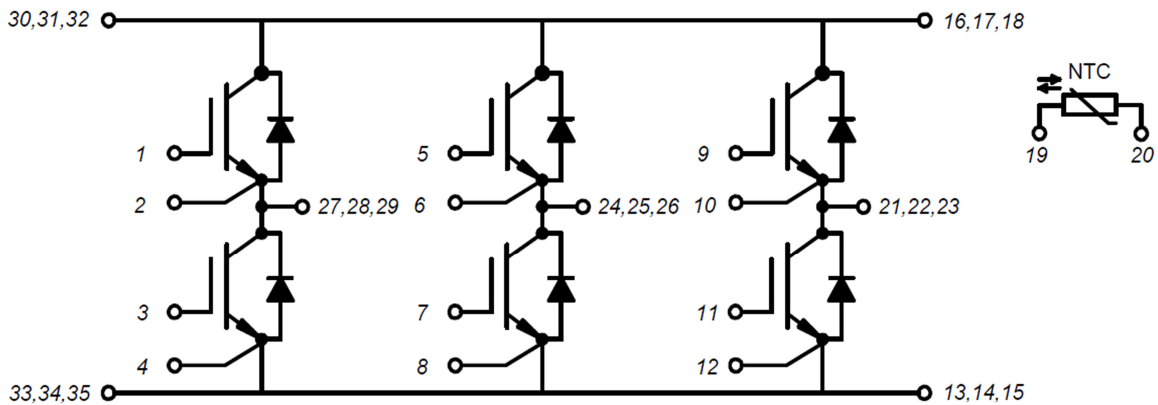


Figure 14. Circuit Diagram

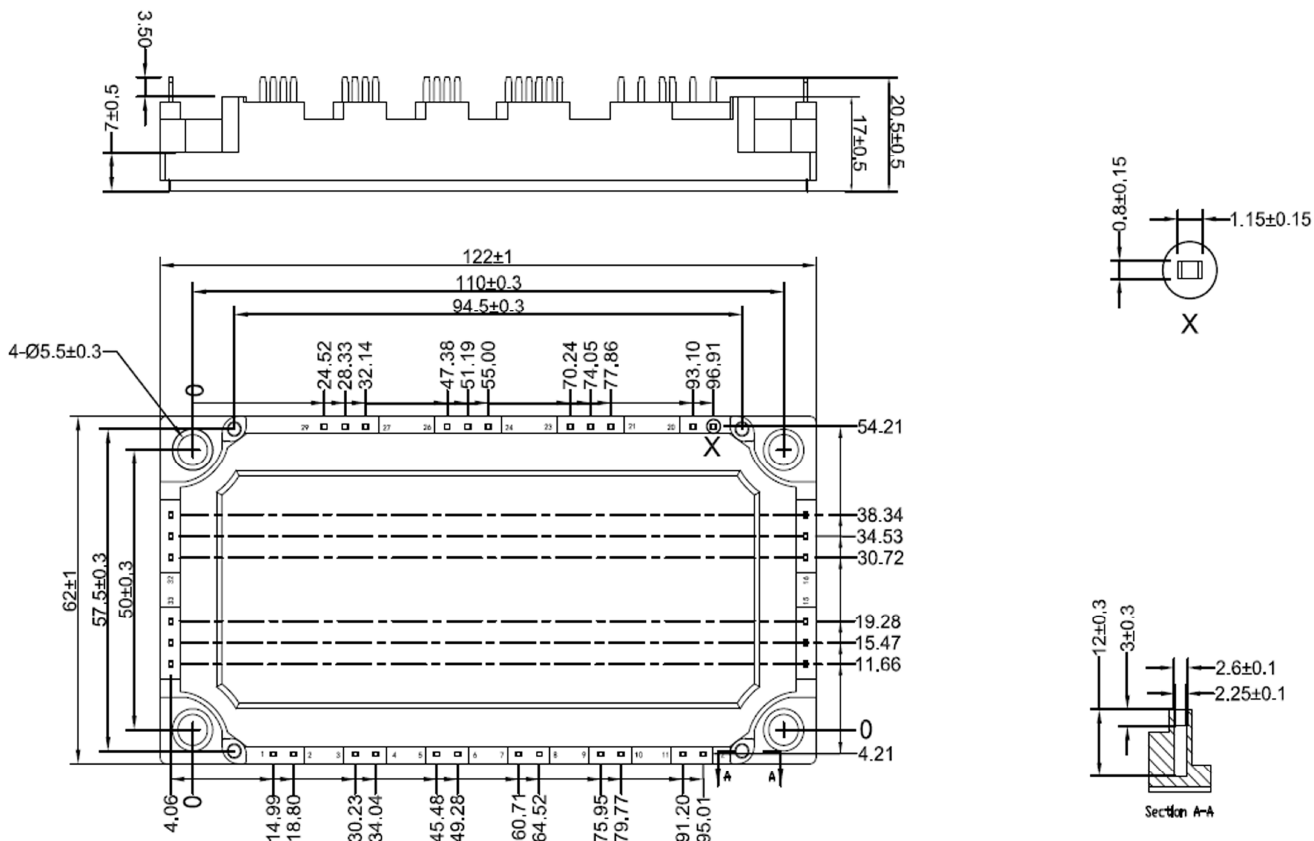


Figure 15. Package Outline